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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10078020	02/15/2002	420	557	1742	<i>Jp Zimmerman</i>

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**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiners's initials		ATTORNEY DOCKET NO END920020007US1
TITLE : Lead-free tin-silver-copper alloy solder composition		

U.S. DEPT. OF COMM./PAT. & TM-PTO-436L(Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING		
Amount Due	Date Paid	Sheets Drwg.	Figs.Drwg.	Print Fig.
TERMINAL DISCLAIMER		Primary Examiner		Application Examiner
PREPARED FOR ISSUE				
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